



#### 3.3V PCI Express<sup>®</sup> 3.0 4 Channel 2x2 Exchange Switch

#### **Features**

- → 4 Differential Channel 2x2 Exchange Switch
- → PCI Express<sup>®</sup> 3.0 performance, 8.0 Gbps
- → Bi-directional operation
- → Low Bit-to-Bit Skew: 10ps (between ± signals)
- → Low Crosstalk: -29dB @ 2.5GHz (5Gbps) -20dB @ 4.0GHz (8Gbps)
- → Low Insertion Loss: -1.1dB @ 2.5GHz (5Gbps) -1.45dB @ 4.0GHz (8Gbps)
- → V<sub>DD</sub> Operating Range: 3.3V ±10%
- → Industrial Temperature Range: -40°C to 85°C
- → ESD Tolerance: 2kV HBM
- → Packaging (Pb-free & Green):
  - <sup>o</sup> 30-contact, TQFN (ZL30), 2.5 x 4.5mm.

#### Description

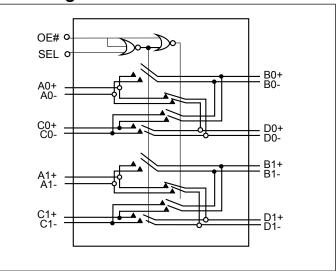
The PI3PCIE3242A is a differential exchange switch featuring pass-through pinout. It supports one full PCI Express<sup>®</sup> lane 2x2 Exchange Switch operating at 8.0Gbps PCIe<sup>®</sup> 3.0 performance.

With the select control input low, Port A connects to Port B, and Port C connects to port D for an 8-channel differential passthough. When the select control input is high Port A connects to Port D, and Port B connects to Port C.

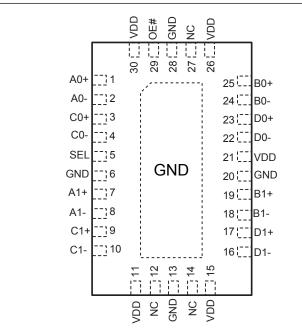
#### **Truth Table**

Function	SEL	OE#
Ax = Bx $Cx = Dx$	0	0
Ax = Dx $Cx = Bx$	1	0
Ax, Bx, Cx, Dx = Hi-Z (disconnect)	x	1

#### **Block Diagram**



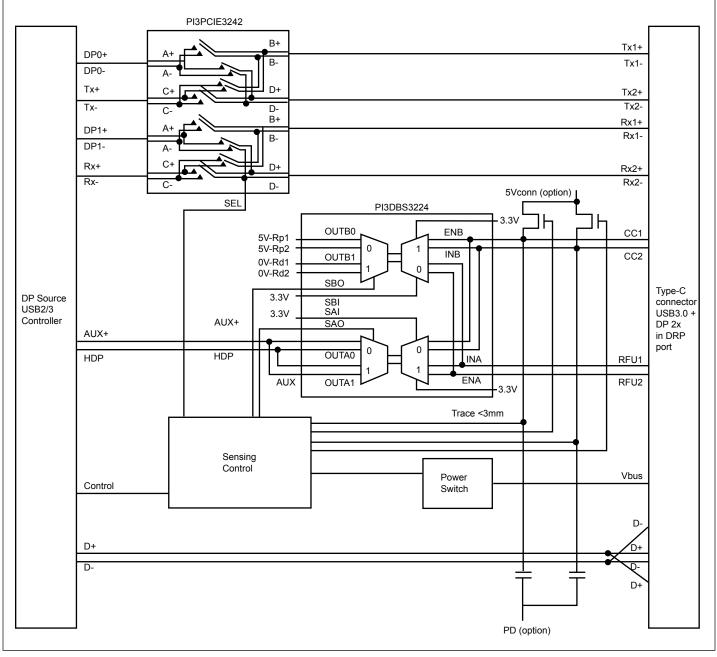
# Pin Diagram 30-TQFN







# Application Diagram in Switching 2 Lanes of DP1.2 & USB 3.0 Signals Over Type C Connector Notebook or Tablet







# Pin Description (30-TQFN)

Pin #	Pin Name	I/O	Description
1	A0+	I/O	Signal I/O, Channel 0, Port A
2	A0-		
7	A1+	I/O	Signal I/O, Channel 1, Port A
8	A1-		
25	B0+	I/O	Signal I/O, Channel 0, Port B
24	B0-		
19	B1+	I/O	Signal I/O, Channel 1, Port B
18	B1-		
3	C0+	I/O	Signal I/O, Channel 0, Port C
4	C0-		
9	C1+	I/O	Signal I/O, Channel 1, Port C
10	C1-		
23	D0+	I/O	Signal I/O, Channel 0, Port D
22	D0-		
17	D1+	I/O	Signal I/O, Channel 1, Port D
16	D1-		
29	OE#	Ι	Output Enable, active low. When OE# = 0 the device I/O is enabled. When OE#=1, all I/O are high impedance
5	SEL	Ι	Operation mode Select (when SEL=0: $A \rightarrow B$ , $C \rightarrow D$ , when SEL=1: $A \rightarrow D$ , $C \rightarrow B$ )
11, 15, 21, 26, 30	V <sub>DD</sub>	Pwr	3.3V ±10% Positive Supply Voltage
6, 13, 20, 28, Center Pad	GND	Pwr	Power ground
12, 14, 27	NC		No Connect





#### **Maximum Ratings**

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	65°C to +150°C
Supply Voltage to Ground Potential	0.5V to +3.7V
DC Input Voltage	–0.5V to V <sub>DD</sub>
DC Output Current	120mA
Power Dissipation	0.5W
Junction Temperature	125°C

**Note:** Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### Electrical Characteristics Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V <sub>DD</sub>	3.3V Power Supply		3.0	3.3	3.6	V
I <sub>DD</sub>	Total current from $V_{DD}$ 3.3V supply	SEL and OE# at OV or $\rm V_{DD}$			200	μΑ
T <sub>A</sub>	Operating temperature range		-40		85	°C

## **DC Electrical Characteristics for Switching over Operating Range**

Parameters	Description	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(1)</sup>	Max.	Units
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed HIGH level	0.65 x V <sub>DD</sub>			
V <sub>IL</sub>	Input LOW Voltage	Guaranteed LOW level	-0.5		0.35 x V <sub>DD</sub>	V
V <sub>IK</sub>	Clamp Diode Voltage	$V_{DD} = Max., I_{IN} = -18mA$		-0.7	-1.2	
I <sub>IH</sub>	Input HIGH Current, SEL	$V_{DD} = Max., V_{IN} = V_{DD}$	-10		+10	
I <sub>IL</sub>	Input LOW Current, SEL	V <sub>DD</sub> = Max., V <sub>IN</sub> = GND	-10		+10	μΑ
IIH	Input HIGH Current, $A_X$ , $B_X$ , $C_{X_1} D_X$	$V_{DD} = Max., V_{IN} = 1.8V$	-10		+10	
IIL	Input LOW Current, AX, BX, CX, DX	$V_{DD} = Max., V_{IN} = 0V$	-10		+10 µA	

Note:

1. Typical values are at VDD = 3.3V, TA = 25°C ambient and maximum loading.

#### **Switching Characteristics**

Parameters	Description	Test Conditions	Min.	Тур.	Max.	Units
t <sub>PZH</sub> , t <sub>PZL</sub>	Line Enable Time - SEL to $A_N$ , $B_N$ , $C_N$ , $D_N$		0.5		45	
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Line Disable Time - SEL to $A_N$ , $B_N$ , $C_N$ , $D_N$		0.5		25	ns
t <sub>b-b</sub>	Bit-to-bit skew within the same differential pair				10	
t <sub>ch-ch</sub>	Channel-to-channel skew		20	ps		





# **Dynamic Electrical Characteristics**

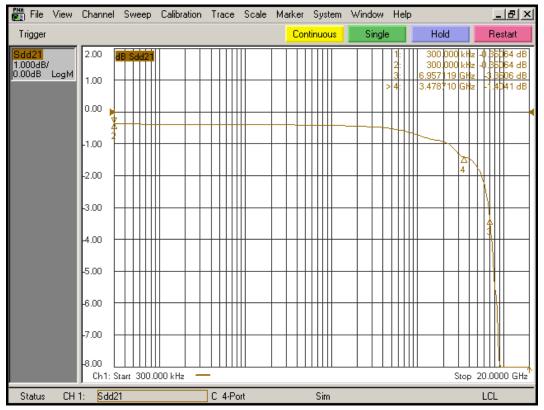
Parameter	Description	Test Conditions	Min.	<b>Typ.</b> <sup>(1)</sup>	Max.	Units
		f=1.2GHz		-0.8	-1.0	
		f=2.5GHz		-1.0	-1.2	
DDIL	Differential Insertion Loss	f=4.0GHz		-1.3	-1.9	dB
	$(V_{IN} = -10 dBm, DC = 0V)$	f=5.0GHz		-1.8	-2.6	
		f=7.5GHz		-4.5	-5.6	
DDIL	Differential Off Isolation	f= 4.0GHz		-19		dB
		f= 0 to 2.8GHz		-26		
DDRL	Differential Return Loss	f= 2.8 to 5.0GHz		-14		dB
		f= 5.0 to 8.0GHz		-7.5		
	Near End Crosstalk	f= 0 to 2.8GHz		-26		
DDNEXT		f= 2.8 to 5.0GHz		-20		dB
		f= 5.0 to 8.0GHz		-16		
		Insertion loss 1.5dB, V <sub>IN</sub> =0.623Vpp, DC=0V		4.0		
V <sub>I F</sub>	Max Signal Frequency Range	Insertion loss 1.5dB, V <sub>IN</sub> =0.623Vpp, DC=0.9V		4.0		GHz
		Insertion loss 3dB, V <sub>IN</sub> =0.623Vpp, DC=0V		8.0		GHZ
		Insertion loss 3dB, V <sub>IN</sub> =0.623Vpp, DC=0.9V		8.0		
BW	-3dB Bandwidth			6.5		GHz

Notes:

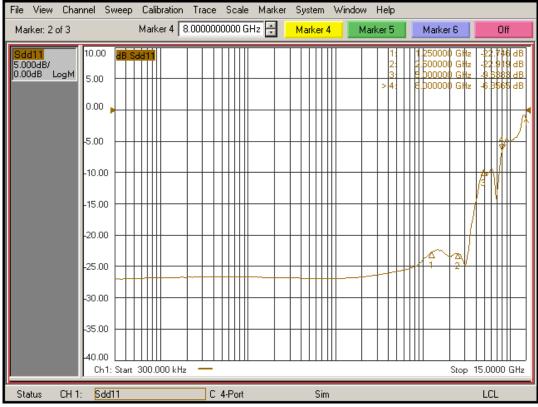
1. Guaranteed by design. Typical values are at  $\rm V_{DD}$  = 3.3V ,  $\rm T_A$  = 25°C ambient and maximum loading.







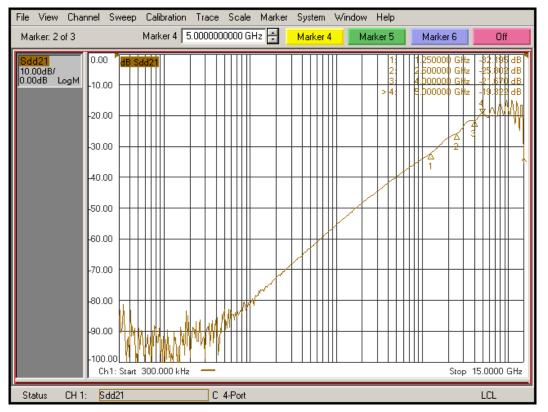
#### **Differential Insertion Loss**



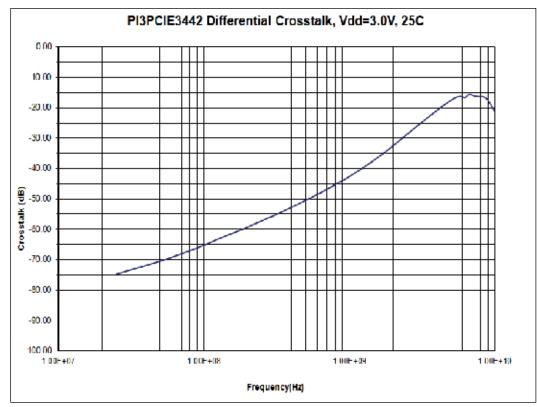
#### **Differential Return Loss**







#### **Differential Off Isolation**

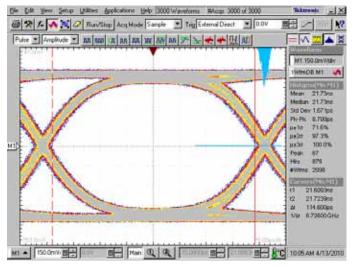


#### **Differential Crosstalk**

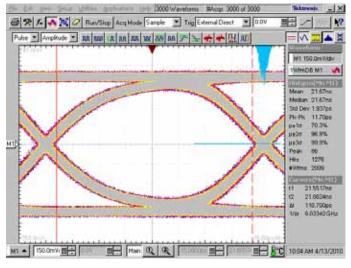


A product Line of Diodes Incorporated

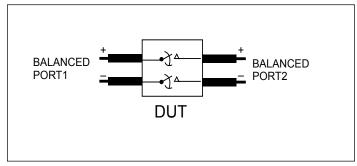
#### PI3PCIE3242A



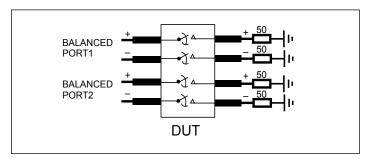
8.0 Gbps RX signal eye without PI3PCIE3242A



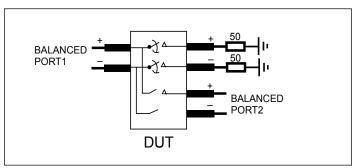
8.0 Gbps RX signal eye with PI3PCIE3242A



Differential Insertion Loss and Return Test Circuit



Differential Near End Xtalk Test Circuit

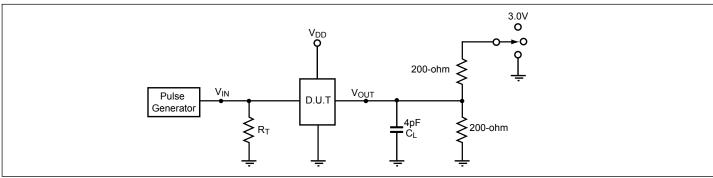


Differential Off Isolation Test Circuit





# Test Circuit for Electrical Characteristics<sup>(1-5)</sup>



Notes:

1. C<sub>L</sub> = Load capacitance: includes jig and probe capacitance.

2. RT = Termination resistance: should be equal to ZOUT of the Pulse Generator

3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control. output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

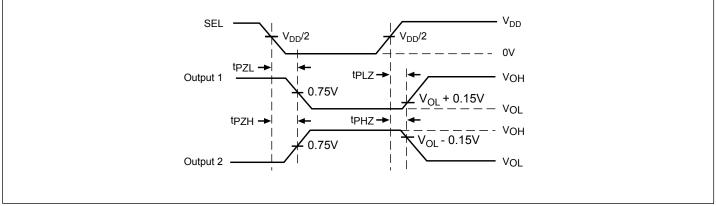
4. All input impulses are supplied by generators having the following characteristics:  $PRR \le MHz$ ,  $Z_O = 50\Omega$ ,  $t_R \le 2.5ns$ ,  $t_F \le 2.5ns$ .

5. The outputs are measured one at a time with one transition per measurement.

#### **Switch Positions**

Test	Switch
$t_{PLZ}, t_{PZL}$	3.0V
t <sub>PHZ</sub> , t <sub>PZH</sub>	GND
Prop Delay	Open

## Switching Waveforms



Voltage Waveforms Enable and Disable Times

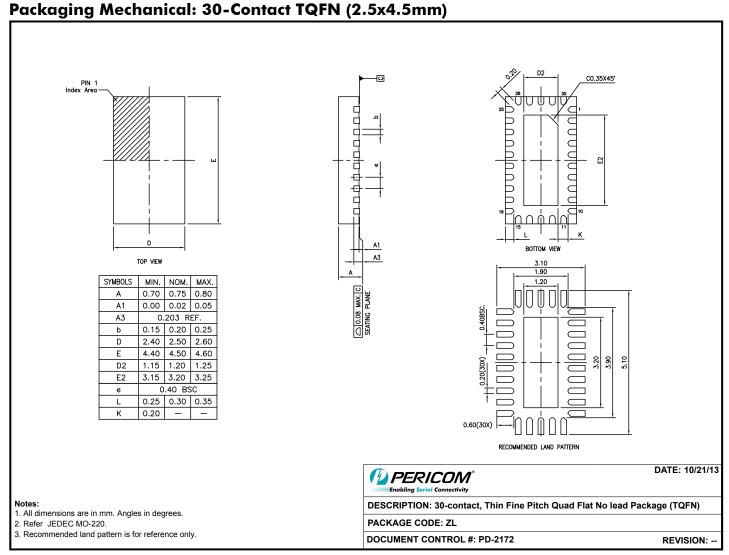
## **Part Marking Information**

**PI3PCIE** 3242AZLE  $\circ$  YYWWX $\overline{X}$ 

YY: Year WW: Workweek 1st X: Assembly Code 2nd X: Fab Code







14-0006

#### For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

## **Ordering Information**

Ordering Code	Package Code	Package Description
PI3PCIE3242AZLEX	ZL	30-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)

#### Notes:

· Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/

• E = Pb-free and Green

• X suffix = Tape/Reel





#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.

Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the

failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2016, Diodes Incorporated

www.diodes.com

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for PCI Interface IC category:

Click to view products by Diodes Incorporated manufacturer:

Other Similar products are found below :

PI7C8150BMA CA91L8260B-100CE PI7C9X2G304ELQZXAEX CH382L XIO2213BIZAY XIO2213BZAY PM8531B-F3EI PI7C9X118SLFDE PM8562B-F3EI PM8574B-FEI PCA9515ADP PI7C8140AMAE PI7C9X20303SLCFDE PM8536B-FEI DS160PR412RUAT DS160PR421RUAR PCI2040PGE PCI2050BPDVG4 PCI2250PCM PCI2250PCMG4 PCI2250PGF XIO1100ZGB XIO2001ZGU PCA9515DP PCX107AVZFU100LC 89H32T8G2ZCBLG 89HPES12NT3ZBBCG PI7C9X113SLFDE PM8533B-F3EI 89HPES12N3AZGBCGI PI7C8150BMAIE I-96 PI7C9X2G304ELZXAE PI7C9X2G304SVAFDEEX PI7C8150AMAE PM8572B-F3EI PI7C9X2G608ELBZXAE TS2PCIE412RUAR XIO1100GGB XIO1100ZWSR